

MATERIAL DECLARATION SHEET

BOURNS®

Material	MF-USML Series
Product Line	Multifuse
Revision Date	May. 3, 2013
Revision	C
RoHS Compliant	Yes
Halogen Free Compliant	Yes

No.	Breakdown of part (eg Lead, Ceramic body, coating, plating, additive)	Material/substance name (eg.Sn alloy, Cu Copper)	Material/ substance weight in grams (±0.1%)	CAS No. / Int. Identifier	Material /substance weight %	Sum(%)
1	Metal Carbide	Titanium Carbide	0.0105332	12070-08-5	44.006%	44.006%
2	Copper Plating	Copper	0.0016969	7440-50-8	7.089%	7.089%
3	Foil	Copper	0.0047480	7440-50-8	19.836%	20.880%
		Nickel	0.0002499	7440-02-0	1.044%	
4	PCB Foil	Copper	0.0024990	7440-50-8	10.440%	10.440%
5	Polymer	Polyethylene Homopolymer	0.0008264	9002-88-4	3.453%	3.458%
		Proprietary Additives	0.0000012	-	0.005%	
6	Prepreg	Epoxy	0.0019160	35948-25-5	8.005%	12.247%
		Glass fiber	0.0010153	65997-17-3	4.242%	
7	Soldering Plating	Tin	0.0004412	7440-31-5	1.843%	1.843%
8	Marking	Epoxy	0.0000059	25068-38-6	0.025%	0.037%
		Titanium Dioxide	0.0000030	1317-80-2	0.012%	
		Total Weight (%)				

Total weight (grams)	0.0239331	Total	100%	100%
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